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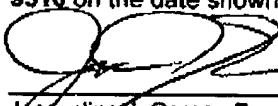
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

I Applicant: Steinmann et al Art Unit: 1765
 Serial No.: 09/852,921 Examiner: Deo, D.
 Filing Date: 05/10/01 Docket No.: TI-29881
 Title: METHOD OF INTEGRATING A THIN FILM RESISTOR IN A
 MULTI-LEVEL METAL TUNGSTEN-PLUG INTERCONNECT

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NAME OF INVENTOR(S): Steinmann TITLE OF INVENTION: Method of Integrating a Thin Film Resistor . . .	
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<small>FAXED:</small> 11/12/2002 <small>DUE:</small> 9/13/2002 <small>ATTY/SECY:</small> JUG	
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